



SOT2022-1

HWFLGA38, thermal enhanced very very thin fine-pitch land grid array package, 38 terminals, 0.35 mm pitch, 4 mm x 3 mm x 0.65 mm body

10 June 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HWFLGA38
Package style descriptive code	LGA (land grid array package)
Mounting method type	S (surface mount)
Issue date	22-03-2021
Manufacturer package code	98ASA01456D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.95	4	4.05	mm
package width	2.95	3	3.05	mm
package height	0.61	0.65	0.69	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	38	-	



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2 Package outline

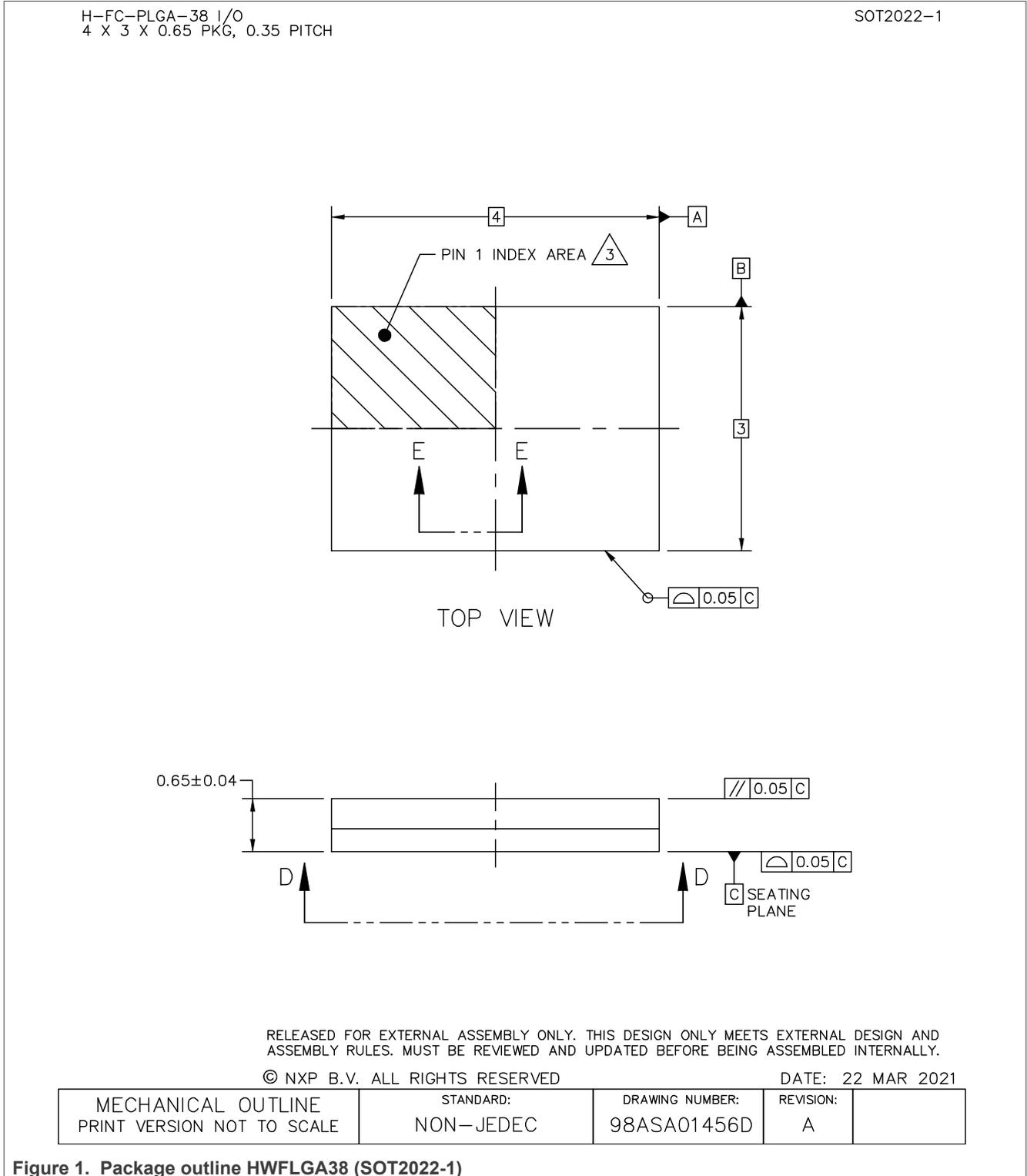


Figure 1. Package outline HWFLGA38 (SOT2022-1)

HWFLGA38, thermal enhanced very very thin fine-pitch land grid array package, 38 terminals, 0.35 mm pitch, 4 mm x 3 mm x 0.65 mm body

3 Soldering

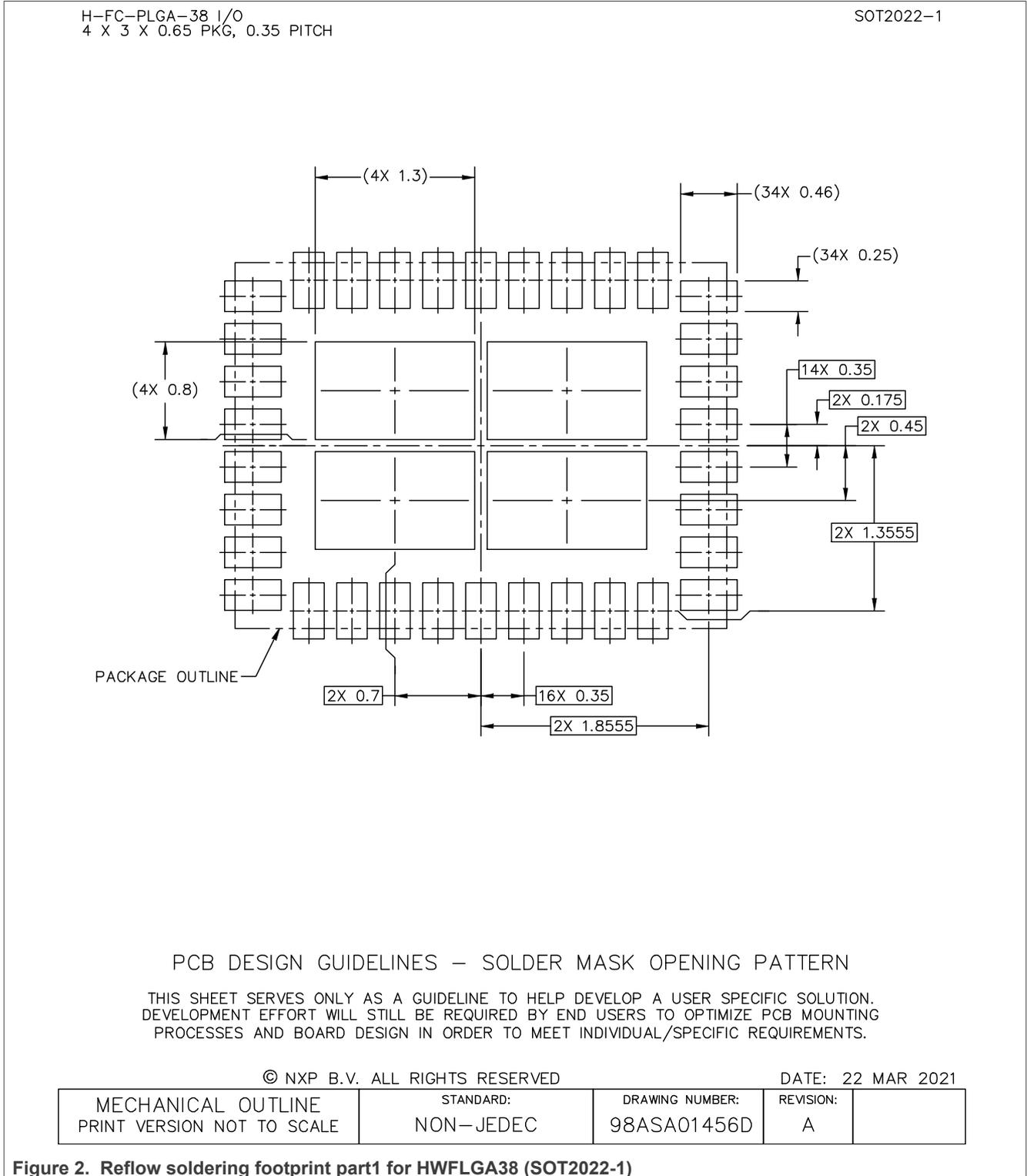


Figure 2. Reflow soldering footprint part1 for HWFLGA38 (SOT2022-1)

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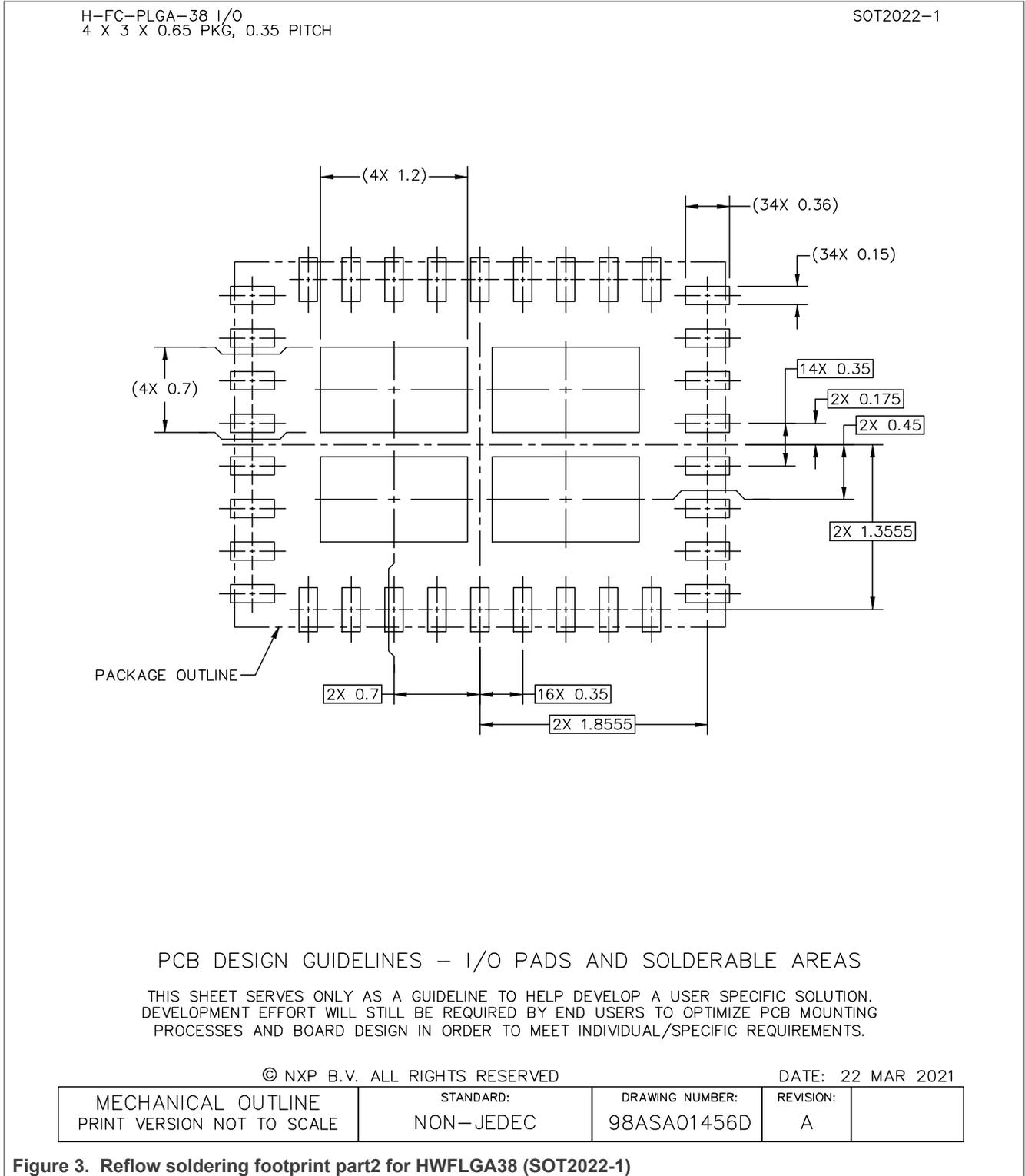


Figure 3. Reflow soldering footprint part2 for HWFLGA38 (SOT2022-1)

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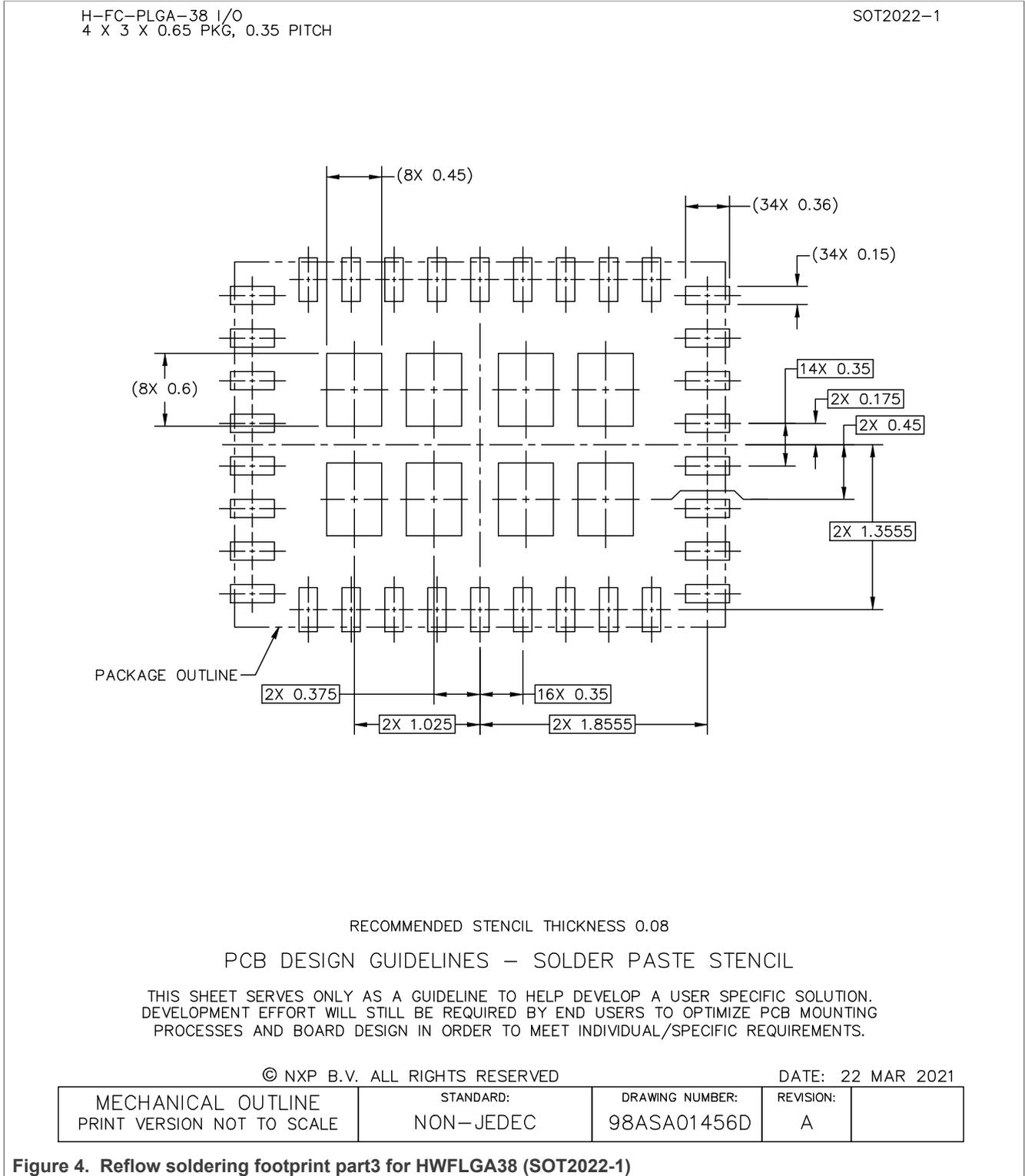


Figure 4. Reflow soldering footprint part3 for HWFLGA38 (SOT2022-1)

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H-FC-PLGA-38 I/O
4 X 3 X 0.65 PKG, 0.35 PITCH

SOT2022-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.

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DATE: 22 MAR 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01456D	REVISION: A	
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Figure 5. Package outline note of HWFLGA38 (SOT2022-1)

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4 Legal information

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